

WCARP **6TH WORLD CONGRESS**
on Adhesion and Related Phenomena

In conjunction with:

41ST ANNUAL MEETING
The Adhesion Society

FEBRUARY 25 – MARCH 1, 2018
Catamaran Resort Hotel • San Diego, California



Award of Excellence Honoree

Ray Pearson, *Lehigh University, USA*

Plenary Speakers

Eduard Arzt, *Leibniz Institute for New Materials, Germany*
Jian Ping Gong, *Hokkaido University, Japan*
Elie Raphael, *ESPCI, France*
Hung-Jue Sue, *Texas A&M University, USA*

Keynote Speakers

Jin-Soo Ahn, *Seoul National University, South Korea*
Arnaud Antkowiak, *Université Pierre et Marie Curie, France*
Kay Blohowiak, *The Boeing Company, USA*
David Bourell, *University of Texas, Austin, USA*
John Connell, *NASA Langley, USA*
Alfred Crosby, *University of Massachusetts, Amherst, USA*
Mark Dadmun, *University of Tennessee, Knoxville, USA*
Pascal Damman, *Université de Mons, Belgium*
Michael Dickey, *North Carolina State University, USA*
Mark Foster, *University of Akron, USA*
David Hays, *3M Company, USA*
Jia Cho Ho, *Industrial Technology Research Institute (ITRI), Taiwan*
Jacob Israelachvili, *University of California, Santa Barbara, USA*
Huda Jerri, *Firmenich, USA*
Pierre Lambert, *Université Libre de Bruxelles, Belgium*
Anke Linder, *ESPCI, France*
Alba Marcellan, *ESPCI, France*
Robin Ras, *University of Alto, Finland*
Gregory Sawyer, *University of Florida, USA*
Manfred Schmid, *ETH Zurich, Switzerland*
Mark Strobel, *3M Company, USA*
Michael Thouless, *University of Michigan, USA*
Yu Tian, *Tsinghua University, China*
Orlin Velev, *North Carolina State University, USA*
Herbert Waite, *University of California, Santa Barbara, USA*

2018 Award, Plenary & Keynotes Announced!

Technical Session and Organizers:

2018 PROGRAM CHAIR

Joelle Frechette, *Johns Hopkins University, USA*

Additive Manufacturing

Michael Bortner, *Virginia Tech, USA*
Amy Peterson, *Worcester Polytechnic Institute, USA*
Erich Bain, *US Army Research Laboratory, USA*

Novel Tools & Methods for Characterization

Chelsea Davis, *Purdue University, USA*
Aaron Forster, *National Institute of Standards & Technology, USA*

Surface Preparation for Bonding

Frank Palmieri, *NASA-LARC, USA*
Dan Knorr, *US Army Research Laboratory, USA*

Transportation

Aaron Mann, *LORD Corporation, USA*
Kay Blohowiak, *The Boeing Company, USA*

Fracture Mechanics

Chenglin Wu, *Missouri University of Science and Technology, USA*
Bamber Blackman, *Imperial College London, UK*

Elasticity and Capillarity in Adhesion

Michael Bartlett, *Iowa State University, USA*
Robert Style, *ETH Zurich, Switzerland*

Materials and Interfaces for Soft Technology

Michael Bartlett, *Iowa State University, USA*
Robert Style, *ETH Zurich, Switzerland*

Gels

Costantino Creton, *ESPCI, France*

Tribology

Frederic Restagno, *Université Paris-Sud, France*
Noshir Pesika, *Tulane University, USA*

Wettability and Surface Interactions

Alidad Amirfazli, *York University, Canada*
Chuck Extrand, *Colder Products Company, USA*

Plasma on Surface and Interfaces

Carlos Barrios, *3M Company, USA*
Mark Strobel, *3M Company, USA*

Particulate Adhesion

Carson Meredith, *Georgia Institute of Technology, USA*

Physical Properties and Design of Bioadhesives

Boxin Zhao, *University of Waterloo, USA*
Dan Sameoto, *University of Alberta, Canada*
Jason Nadler, *Georgia Institute of Technology, USA*

Bioadhesive Chemistry

Niels Holten-Andersen, *Massachusetts Institute of Technology, USA*
Haeshin Lee, *Korea Advance Institute of Science and Technology, Republic of Korea*
Terry Steele, *Nanyang Technological University, Singapore*

Organismal Adhesion

Alyssa Stark, *Villanova University, USA*
Alexis Noel, *Georgia Institute of Technology, USA*

Biomedical Adhesives and Clinical Applications

Bruce Lee, *Michigan Technological University, USA*
Kolbe Ahn, *University of California, Santa Barbara, USA*
Yuhan Lee, *Harvard Medical School, USA*

Adhesives for Electronics

Chris Campbell, *3M Company, USA*
Arlin Weikel, *Corning, Inc., USA*

Rheology

Ali Dhinojwala, *University of Akron, USA*
Vivek Sharma, *University of Illinois at Chicago, USA*

Novel Chemistry

Karl Benson, *3M Company, USA*
Scott Phillips, *Boise State University, USA*

Innovative Polyurethane Adhesives

José Miguel Martín Martínez, *Laboratorio de Adhesión y Adhesivos Universidad de Alicante, Spain*

CALL FOR ABSTRACT, SUBMISSIONS

Abstract deadline:
September 15, 2017

We strongly encourage you to submit an abstract for the 2018 Annual Meeting being held on February 25-March 1 in conjunction with the 6th World Congress on Adhesion and Related Phenomena at the Catamaran Resort Hotel.

You can submit an abstract at www.adhesionsociety.org/.

If you have any questions regarding the relevant topics, please contact Joelle Frechette at jfrechette@jhu.edu. For questions regarding submissions, please contact Malinda Armstrong at adhesionsociety@ascouncil.org.

PEEBLES & POSTER AWARDS – SEE WEBSITE FOR SUBMISSION AND QUALIFICATIONS.

WWW.ADHESIONSOCIETY.ORG